# Wire Bondable Voltage **Divider Network**



### **DSOT Series**

- · Tight TCR tracking
- · Extremely small footprint
- Precision ratio tolerances to ±0.05%
- Ultra-stable tantalum nitride resistors

IRC's TaNSil® voltage divider networks are ideally suited for low cost divider applications that demand precision performance in a wire bondable package.

The tantalum nitride film system on silicon provides precision tolerance, exceptional TCR tracking and miniature physical dimensions. Excellent performance in harsh, humid environments is a trademark of IRC's selfpassivating TaNSil® resistor film.

For applications requiring high performance voltage dividers in a miniature, wire bondable package, specify IRC DSOT wire bondable die.

### **Electrical Data**

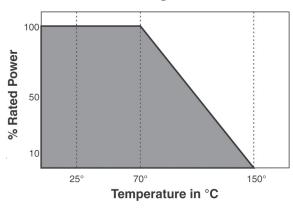
Resistance Range E	10 $\Omega$ to 500K $\Omega$		
Resistance Range E	to 1.0M $\Omega$		
Absolute Tolerance	to ±0.1%		
Ratio Tolerance to F	to ±0.05%		
Absolute TCR		to ±25ppm/°C	
Tracking TCR		to ±5ppm/°C	
Element Power Rati	ng	125mW @70°C	
Package Power Rati	ing	250mW @ 70°C	
Rated Operating Volume (not to exceed $\sqrt{P}$ x	Itage R)	100V	
Operating Temperat	ure	-55°C to + 150°C	
Noise		<-30dB	
Substrate Material		Oxidized Silicon (10KÅ SiO <sub>2</sub> minimum)	
Substrate Thickness		0.0095" ±0.001 (0.241mm ±0.025)	
Bond Pad	Aluminum	10KÅ minimum	
Metallization	Gold	15KÅ minimum	
Backside		Silicon (gold available)	
Passivation		Silicon Dioxide or Silicon Nitride	

## TCR/Inspection Code Table

Absolute TCR	Commercial Code	MIL Inspection Code*
±300ppm/°C	00	04
±100ppm/°C	01	05
±50ppm/°C	02	06
±25ppm/°C	03	07

<sup>\*</sup>Notes: Product supplied to Class H of MIL-PRF 38534 include 100% visual inspection

## Power Derating Data



### **General Note**

IRC reserves the right to make changes in product specification without notice or liability. All information is subject to IRC's own data and is considered accurate at time of going to print.



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# Manufacturing Capabilities Data

Resistance Range	Available Absolute Tolerances	Available Ratio Tolerances	Best Absolute TCR	Tracking TCR
10Ω - 50Ω	FGJK	DFGJK	±100ppm/°C	±50ppm/°C
51Ω - 100Ω	DFGJK	CDFGJK	±100ppm/°C	±25ppm/°C
101Ω - 200Ω	CDFGJK	BCDFGJK	±50ppm/°C	±10ppm/°C
201Ω - 500Ω	BCDFGJK	BCDFGJK	±50ppm/°C	±5ppm/°C
501Ω - 1.0ΜΩ	BCDFGJK	ABCDFGJK	±25ppm/°C	±2ppm/°C

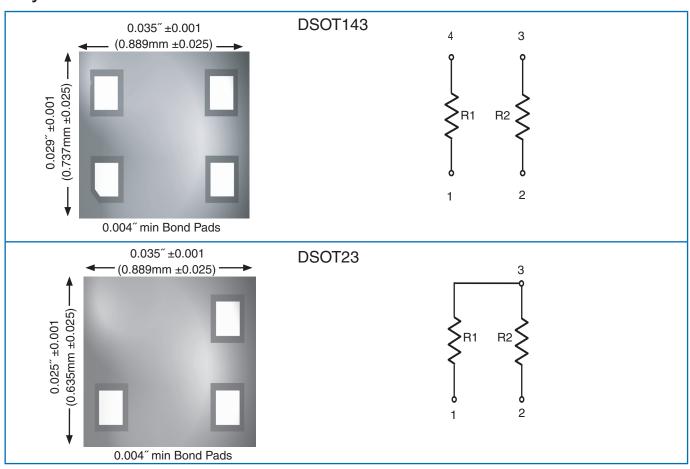
# **Environmental Data**

Test	Method	Max ∆R	Typical ∆R
Thermal Shock	MIL-STD-202 Method 107 Test condition F	±0.1%	±0.02%
High Temperature Exposure	MIL-STD-883 Method 1008 150°C, 1000 hours	±0.1%	±0.05%
Low Temperature Shortage	-55°C, 1000 hours	±0.03%	±0.01%
Life	MIL-STD-202 Method 108 70°C, 1000 hours	±0.5%	±0.01%
Life at Elevated Temperature	MIL-STD-202 Method 108 125°C, 1000 hours	±0.5%	±0.05%

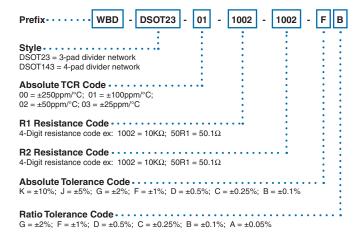
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# Physical Data



## **Ordering Data**



#### Packaging

Standard packaging is 2" x 2" chip tray. For additional information or to discuss your specific requirements, please contact our Applications Team using the contact details below.